

# MODEL ATM-3000EF

## Automatic Wafer Lamination System

### Outline

The ATM-3000EF is the ideal system for laminating tape to wafers, for the backgrind process and dry resist film lamination process.

### Features

- State-of-the-art design to maintain the integrity of the lamination area and to achieve the best footprint.
- Ergonomic design for optimum access to operator areas and service areas on the system
- Tape stretch data control.
- Ease of operation
- FOUF option
- AGV and OHT protocol options
- Applicable to 8" and 12" dia-wafer
- Heater roller and heater table are applicable

For  
**300mm**  
wafers



Specification		ATM-3000EF
Throughput		42 wafers/hour (Depend on data setting and tape)
Wafer Size		8 inch, 12 inch
Tape Width		8 inch :W 225mm , 12 inch :W 330mm
Utilities	Power	AC100V Single phase 60Hz 4.0 KVA
	Air	Pressure 0.4Mpa 100NI/min
	Vacuum source	-80Kpa
Dimensions		D 1,625 × W 1,350 × H 1,800mm
Weight		Approx. 600 kg

System appearance and specifications are subject to change without prior notice from the supplier.

313-1 Shindo-cho, Kashihara City, Nara, Japan 634-8580

Phone: +81 (0) 744-24-7670

Fax: +81 (0) 744-24-8352

URL <http://www.takatori-g.co.jp> E-mail [info@takatori-g.co.jp](mailto:info@takatori-g.co.jp)